Electronic Patent Application Fee Transmittal

Application Number:	10678489
Filing Date:	03-Oct-2003
Title of Invention:	Method and arrangement for reduced thermal stress between substrates
First Named Inventor/Applicant Name:	Vahid Goudarzi
Filer:	Larry G. Brown/Silvana Wiltshire
Attorney Docket Number:	CE11821JME

Filed as Large Entity

Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD($)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Filing a brief in support of an appeal	1402	1	500	500
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD($)
Miscellaneous:				
			Total in USD ($)	**500**